

**SINLOON®** 

se: TO-220A

SB820 - SB8100

8.0A Schottky Barrier Rectifier

# Feature

- ◆ Schottky Barrier Chip
- Guard Ring for Transient Protection
- ◆ Low Forward Voltage Drop
- ◆ Low Reverse leakage Current
- High Surge Current Capability
- Plastic Material has UL Flammability Classification 94V-0

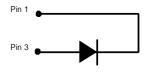
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- ◆ Case: TO-220A, Full Moldes Plastic
- ◆ Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- ◆ Polarity: See Diagram
- ◆ Weight: 2.24 grams (approx)
- Mounting Position: Any
- ◆ Mounting Torque: 11.5 cm-kg (10 in-lbs) max.
- ◆ Lead Free: For RoHS / Lead Free Version Add "-LF" Suffix to part Number.

### Figure



## □ Electrical Sambol



### □ Dimension

K

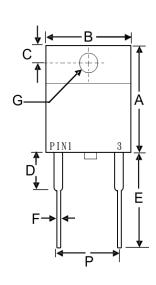
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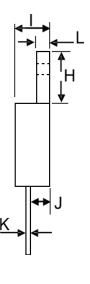
Case: TO-	(mm)		
Dim.	Min.	Max.	
Α	13.9	15.9	
В	9.8	10.7	
С	2.54	3.43	
D	3.56	4.56	
Е	12.7	14.73	
F	0.51	0.96	
G (Φ)	3.55	4.09	
Н	5.75	6.85	
I	4.16	5.0	
J	2.03	2.92	

0.3

1.14

4.83





# ■ Marking Information

SB8xx = Device Number

= See Page 2 SB Part XX

0.65

1.4

5.33

**Polarity** = As Marked Body









肖特基二極管

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# ☐ Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25℃ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load For capacitive load, derate current by 20%.

					,		· · <b>,</b> · · ·			
Characteristics	Symbol	SB 820	SB 830	SB 840	SB 845	SB 850	SB 860	SB 880	SB 8100	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	020	030	040	040	030	000	000	0100	
Working Peak Reverse Voltage	V <sub>RWM</sub>	20	30	40	45	50	60	80	100	V
DC Blocking Voltage	VRVIVI	20	00	10	10			00	100	
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	32	35	42	56	70	V
Average Rectified Output Current @T <sub>L</sub> =9	Io		8.	0		8.	0	8.	.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC	I <sub>FSM</sub>	150			1	50 150		50	А	
Forward Voltage @I <sub>F</sub> =8.0A	$V_{FM}$	0.55		0.75		0.85		V		
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Vol. $@T_A=100^{\circ}C$	I <sub>RM</sub>	0.5 50						mA		
Typical Junction Capacitance (Note 1)	C <sub>i</sub>	700						pF		
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	3.0					°C/W			
Operating and Storage Temperature Ran	$T_i, T_{STG}$	-65 to +150						$^{\circ}\!\mathbb{C}$		
Note 1: Managered at 1 0 MHz and an	plied revers	o voltog	o of 4 0	VDC						-

Note 1: Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

Fig-3 Maximum Non-Repetitive Paek FWD Surge Current

Note 2: Thermal resistance junction to case mounted on heatsink.

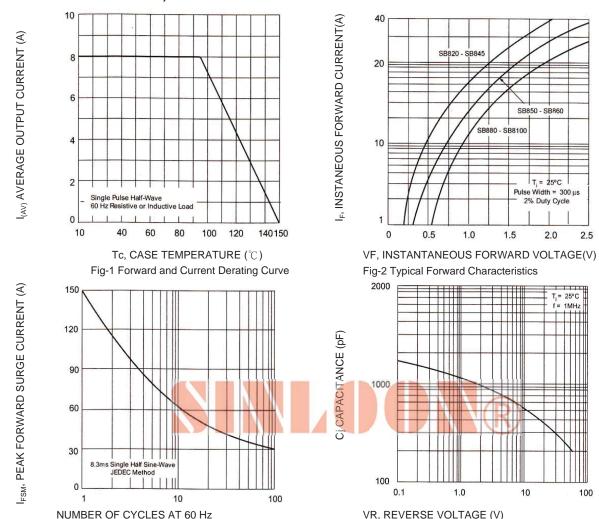


Fig-4 Typical Junction Capacitance



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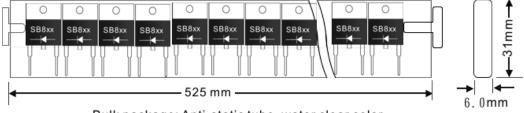
Packaging Information

Tube Size	Quantity	Inner Box Size	Quantity	Carton Size	Quantity	Gross
LxWxH (mm)	(Pcs)	LxWxH (mm)	(Pcs)	LxWxH (mm)	(Pcs)	Weight
525 x 31 x6	50	555x145x95	2000	572x306x218	8000	19.0kg

Note: Anti-static tube. Water clear color.

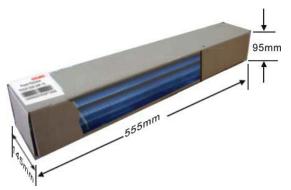
♦ Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

#### Anti-static tube:

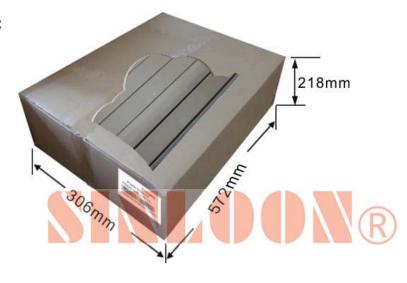


Bulk package: Anti-static tube, water clear color.

#### Inner Box:



### **Carton Package:**



- ※美隆公司產品規格及其特性參數的改變或更新恕不另行通知。
- Mayloon characteristic parameters of electronic product specification changes or updates without notice to improve •







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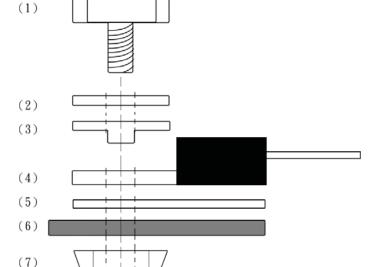
### ☐ Package Mounting Guide

It is important that the packages are correctly mounted if full functionality is to be achieved. Mounting of the package to a heat sink must be done such that there is sufficient pressure from the mounting screws to insure good contact with the heat sink for efficient heat flow. Incorrect mounting may lead to both thermal and mechanical problems. Over tightening the mounting screws will cause the package to warp reducing the contact area with the heat sink and increasing the thermal resistance from the package case to the heat sink, resulting in higher operating die temperatures. Extreme over tightening of the mounting screws beyond the recommended torque force will cause severe physical stress resulting in cracked die and catastrophic IC failure. Though the reliability of the package is excellent, the use of inappropriate techniques or unsuitable tools during the mounting process can affect the long term reliability of the device and even damage it.

#### □ Recommended Screw Mount Arrangement



(1) 4-40 Pan or HEX Head Screw



- (2) Plain Washer
- (3) Insulating Bushing
- (4) Rectifier
- (5) Insulator
- (6) Heat sink
- (7) Compression Washer
- (8) 4-40 HEX Nut
- ◆ Recommended isolated mounting when screw is at heat sink potential,4-40 hardware is used.
- ♦ Screw should not be tightened with any type of air-forced torque or equipment that may cause high impact on device package. The insulating bushing inside the mounting hole will insure the screw threads do not contact the metal base.
- ◆ The interface should apply a layer of thermal grease or a highly conductive thermal pad for better heat dissipation

<sup>\*</sup>Mayloon characteristic parameters of electronic product specification changes or updates without notice to improve



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